



2026.07.03

法人說明會 Investor Conference

鑫科材料科技股份有限公司

ThinTech Materials Technology Co., Ltd.(TTMC)





議 程

- 致歡迎詞及團隊介紹
Welcome speech and team introduction
- 2026Q1營運現況
2026Q1 Operation
- 重點產品與營運展望
Product Highlights and operation outlook
- 提問與回答
Questions and Answers

李建輝 董事長
Chairman C.H. Lee

許銘璫 行政副總
Adm. VP M.T. Hsu

葉長生 總經理
President C.S. Yeh

經營團隊
Management team



投資安全聲明

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經營團隊 Management team



董事長
Chairman



李建輝
C.H. Lee

- 中鴻鋼鐵(股)公司行政副總經理
VP of Adm., Chung Hung Steel Corporation
- 中龍鋼鐵(股)公司財務副總經理
VP of Finance, Dragon Steel Corporation
- 越南中鋼住金(股)公司管理副總經理
VP of Adm., Vietnam CSC & Sumitomo Metal Corporation

總經理 &
中鋼精材董事長
President &
Chairman of CSPM



葉長生
C.S. Yeh

- 中鋼智財與檢測技術處處長
General Manager,
Intellectual Property &
Testing Technology
Dept., CSC

生產技術副總
Vice President
of Production
Technology



林景扶
Jeff Lin

- 工業技術研究院研究員
Researcher, Industrial
Technology Research
Institute

行政管理副總
Vice President of
Administration



許銘璉
M.T. Hsu

- 中鋼工業工程處 經營發展組組長
Manager, Business
Development
Section, Industrial
Engineering
Department, CSC



I. 關於鑫科(TTMC) Company Profile



2000成立 founded 2006遷入高科園區 move to KHH Science Park 2012 上櫃 TWSE OTC (3663)	Employers員工數(2026) 209(TTMC/TWN)鑫科 171(CSPM/China)精材 	Capital 資本額(2025) NT\$1,085M Revenue 合併營收 NT\$5,715M Major Holders 主要股東(2026) CSC Group 中鋼集團(51.15%) URECO 聯合再生(6.45%) 	QC/OHSMS品保/環安衛 ISO 9001 ISO 45001 ISO 14001 ISO 17025 IECQ-QC 080000 IATF 16949 AEO												
Location廠址 TTMC鑫科 KHH Sci. Park1, Luke 8th Rd., Lujhu District, Kaohsiung, TWN CSPM常州中鋼精材 (Changzhou, Jiangsu, China) Plant area : 30,000m2 ; Phase 1 : 2 Building , 18000m2 , Phase 2 : 12000m2 available	Southern Taiwan Technology Corridor 	Main products 主要產品 <table><tr><td>Sputtering Targets濺鍍靶材</td><td>Other products其他</td></tr><tr><td>TFT LCD/Touch panel (Flat/tube, Al, Mo, Cu, Ti)</td><td>Biomedical composites (BNCT moderator)</td></tr><tr><td>Optical data storage (ZnS, TRA-, TRB- series)</td><td>Parts Cleaning (Au, Ag...)</td></tr><tr><td>Crystal Oscillators/ Passive component (Ag, Ag-alloy series)</td><td>Sputtering parts (Taiko ring, sliding plate, FOPLP carrier...)</td></tr><tr><td>Tool/Decoration (Al, Cu, Ti, Ni-alloy series)</td><td>Industrial Ni-base alloy (Pickling hook, Furnace)</td></tr><tr><td>Semiconductor (Al-Cu, Ti, NiV, Ag, Au series)</td><td>Ti-base alloy (3C frame, Cu foil roller, roof, curtain wall)</td></tr></table>		Sputtering Targets濺鍍靶材	Other products其他	TFT LCD/Touch panel (Flat/tube, Al, Mo, Cu, Ti)	Biomedical composites (BNCT moderator)	Optical data storage (ZnS, TRA-, TRB- series)	Parts Cleaning (Au, Ag...)	Crystal Oscillators/ Passive component (Ag, Ag-alloy series)	Sputtering parts (Taiko ring, sliding plate, FOPLP carrier...)	Tool/Decoration (Al, Cu, Ti, Ni-alloy series)	Industrial Ni-base alloy (Pickling hook, Furnace)	Semiconductor (Al-Cu, Ti, NiV, Ag, Au series)	Ti-base alloy (3C frame, Cu foil roller, roof, curtain wall)
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I. 產品發展軌跡 Products Development Trace



光儲存媒體
ODS



裝飾及被動元件
DEC & PAC



面板/顯示器
Display



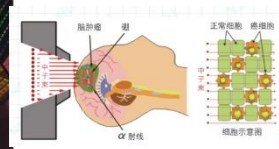
晶體振盪器
OSC



半導體
SEMI



鋁基複材
Moderator



特殊合金
Ti/Ni



2000

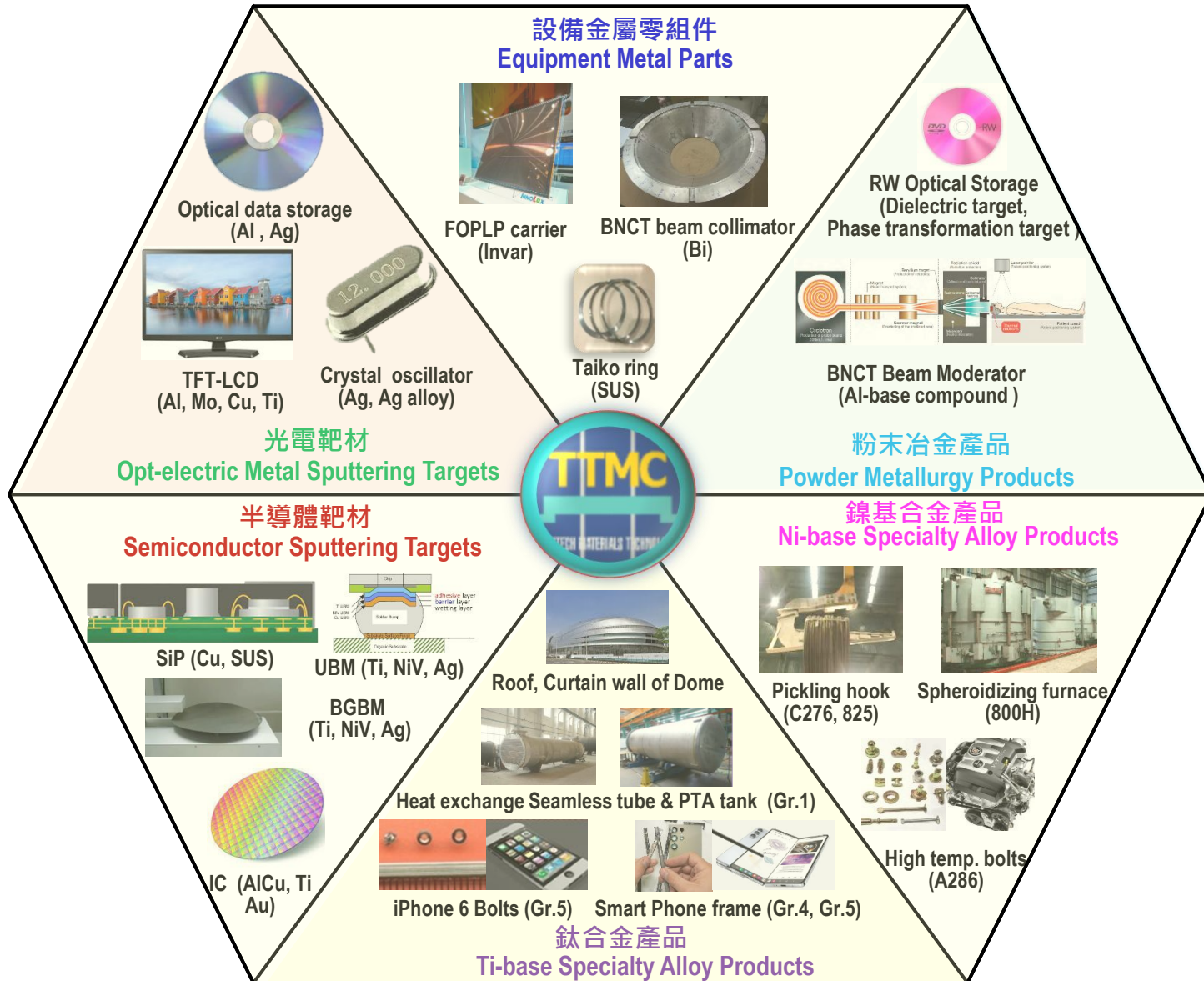
2005

2010

2021

2024

- 鑫科早期(2000~2005)以光碟片用銀、鋁、介電靶起家；2006~2020則以面板為主，擴及裝飾鍍、被動元件及石英震盪用鋁、鉬、銅、鈦靶；2021~2023則開始發展半導體用靶材，策略為製程由後向前、尺寸由小至大、涵蓋純矽及化合物。2024除跨入醫療用鋁基複材，也跨足鈦/鎳特殊合金及面板級扇出型封裝用Fe-Ni合金載板。
- Early(2000~2005) : Focus on Optical data storage (ODS) targets (Ag, Al, Dielectric)
- Middle(2006~2020) : Extend to optical targets for decoration(DEC), passive components(PAC), Display, Crystal Oscillators (OSC) (Al, Mo, Cu, Ti)
- Near(2021~2023) : Launch into semiconductor(SEMI) industry, strategy: process from back to front end, size from small to large, and application for both Si & compound semiconductor.
- Now(2024~) : Extend the application of Al-based composites and Specialty Ti/Ni Alloys, such as FOPLP Fe-Ni carrier plate and Smartphone Ti frame.





I.營運概況 Operational Overview



-近期重要紀事 Recent important events

- 公司已成為面板級扇外型封裝（FOPLP）金屬載板的唯一技轉認可供應商，並擴大供貨至歐美客戶，且成功將產品線延伸至晶圓載具；同時，亦為 AB-BNCT 硼中子捕獲治療之減速材料獨家供應商。此外，廠內大型設備已建置完成，全面具備自主生產能力。

TTMC has become the sole tech-transfer certified supplier of metal substrates for panel-level fan-out (FOPLP) packaging, with product lines successfully expanding into European, American and customer of wafer carriers. Additionally, it serves as the exclusive supplier of moderating materials for AB-BNCT. With the installation of large-scale facility equipment completed, TTMC has fully established its in-house production capacity.

- 半導體前段製程產品已有初步斬獲，已陸續通過驗證與稽核，具備龐大成長潛力；將持續攜手戰略夥伴拓展市場。

TTMC have made initial successes with our semiconductor front-end process products, which have passed verification and audits and have great growth potential. TTMC will continue to work with our strategic partners to expand the market.

- 第十二屆(114年)公司治理評鑑，本公司位列全體上櫃公司第二級距，連續七年位列第二級距，總分達95.52歷年來最高。

In the 12th (2025) Corporate Governance Assessment, the Company was ranked in the second of all OTC companies, and has been ranked in the second tier for seven consecutive years, with a total score of 95.52 the highest on record.

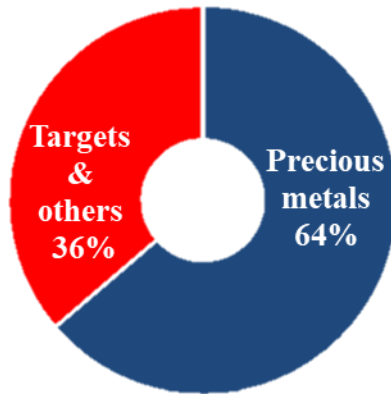


I. 營運概況 Operational Overview

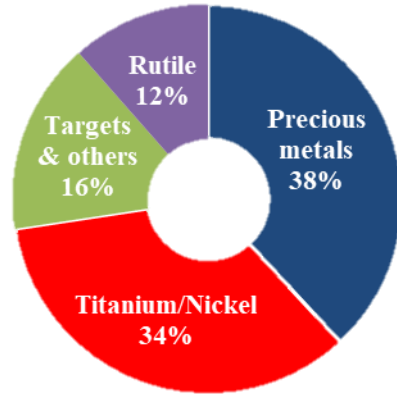
-產品營收比率 Sales Revenue Ratio by Product



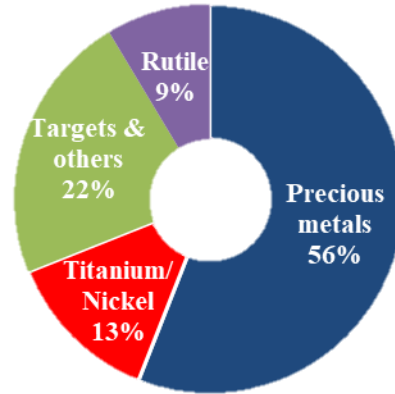
2023



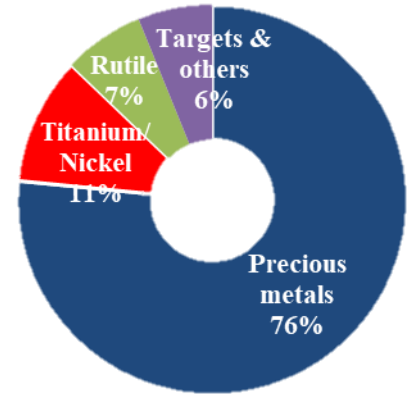
2024



2025



2026 Q1



繼2024年併購中鋼精材後，本公司擴大了產品組合，納入鈦合金及鎳基特種合金，從而提升產品多樣性。然而，受2025年至2026年第一季間避險情緒升溫及工業需求強勁所驅動，貴金屬價格與銷量雙雙上揚，導致貴金屬在本公司產品組合中的占比隨之增加。

Following the acquisition of CSPM in 2024, the Company expanded its product portfolio to include titanium and Ni-based specialty alloys, enhancing product diversification. However, rising precious metal prices and sales volumes, driven by stronger safe-haven sentiment and industrial demand from 2025 through 2026 Q1, increased the share of precious metals in the Company's product mix.

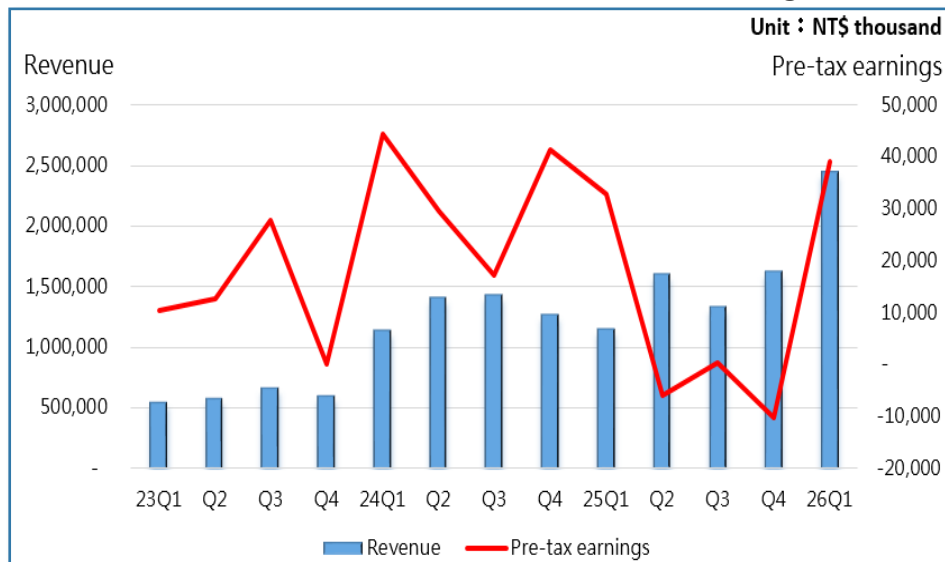


I. 財務績效 Financial Performance

- 合併營收及淨利 Consolidated revenue and Earnings



鑫科材料 合併營收與稅前淨利
TTMC Revenue and Pre-tax earnings



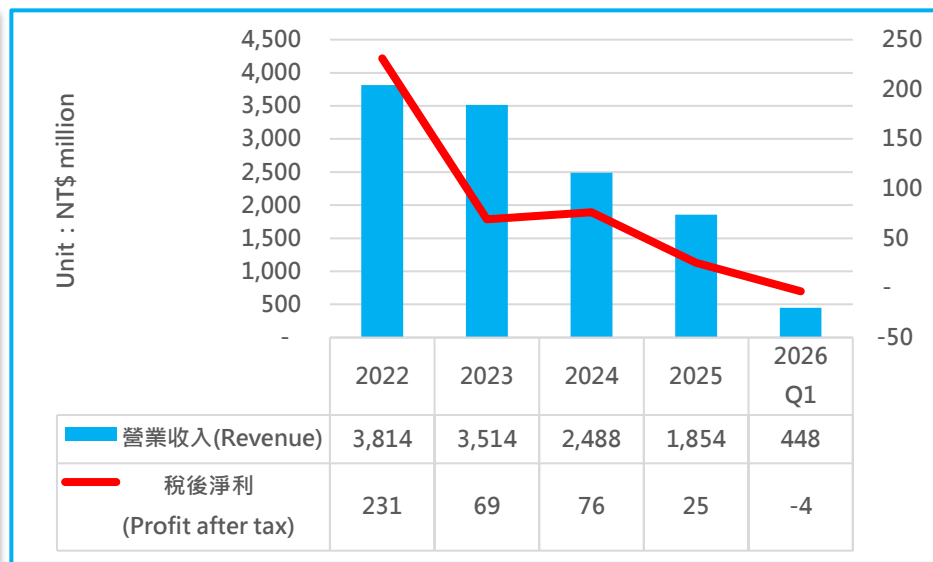
2026Q1營收新台幣2,449 百萬元；稅前淨利新台幣39百萬元。

2026Q1 Revenue : NTD 2,449 million ; Pre-tax earnings : NTD 39 million.

2026/4~5營收新台幣987百萬元。

2026/4~5 Revenue : NTD 987 million .

中鋼精材 稅後淨利
CSPM Profit after tax



2026年市場需求仍顯疲弱，加上產業競爭日趨激烈，導致中鋼精材2026年第一季稅後淨損新台幣360萬元。惟公司持續推動高附加價值產品開發、製程優化及成本改善等措施，成效已逐步顯現，預期第二季稅後淨利可望轉虧為盈。

CSPM reported a net loss after tax of NT\$3.6 million for the first quarter of 2026. Through measures such as process optimization and cost reductions, the company is expected to return to profitability in the second quarter.



I. 中鋼精材整併 Mergement of CSPM

-中鋼精材市況與發展 Market situation and development of CSPM

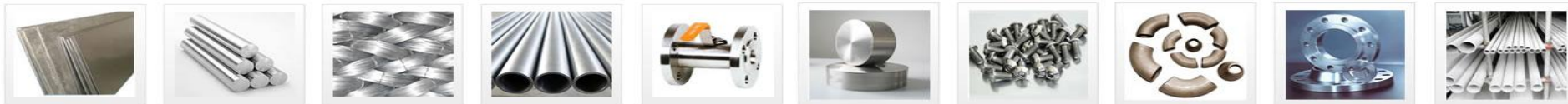


2026年以來，中國經濟復甦力道不如預期，房地產、石化及一般工業投資成長趨緩，終端需求疲弱持續影響製造業發展。

1. 鈦材市場雖受海綿鈦價格上漲支撐，整體價格維持高檔震盪，但下游需求未明顯回溫，市場競爭依然激烈。
2. 鎳基合金市場則受產能過剩、需求不足及低價競爭影響，產品售價難以充分反映原料成本波動，整體經營環境仍相當嚴峻。

Since 2026, China's economic recovery has been weaker than expected. Sluggish investment growth in the real estate, petrochemical, and general industrial sectors, coupled with soft end-market demand, has continued to weigh on manufacturing activity.

1. In the titanium market, rising sponge titanium prices have provided cost support, keeping prices at relatively elevated levels; however, downstream demand has yet to recover meaningfully, and market competition remains intense.
2. The nickel-based alloy market continues to face challenges from excess capacity, weak demand, and aggressive price competition, making it difficult for product prices to fully reflect fluctuations in raw material costs. As a result, the overall business environment remains highly challenging.





I. 中鋼精材整併 Mergement of CSPM

-中鋼精材市況與發展 Market situation and development of CSPM

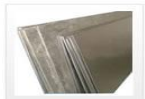


面對市場挑戰，中精持續深化產品結構調整與技術升級：

1. 穩定發展鈦及鈦合金核心業務，積極推動TA10、GR9等高毛利產品及大型荒管市場開發；
2. 加速半導體靶材、Ni93V7高值化產品及利基型鎳基合金產品布局，提升產品附加價值與市場競爭力。
3. 公司持續推動品質改善、製程精進及成本優化，並藉由110kV變電站建設、鎳基鑄錠品質提升及關鍵製程改善等專案，強化長期發展基礎，逐步提升公司整體獲利能力與經營績效。

In response to these market conditions, CSPM has continued to advance product portfolio optimization and technological upgrades.

1. The Company remains focused on strengthening its core titanium and titanium alloy business while actively promoting high-margin products such as TA10 and Grade 9 alloys, as well as expanding its large-diameter billet market.
2. Efforts have been accelerated to develop semiconductor sputtering targets, high-value-added Ni93V7 products, and niche nickel-based alloy applications, thereby enhancing product value and market competitiveness.
3. The Company continues to drive quality improvement, process optimization, and cost-reduction initiatives. Key projects, including the 110kV substation construction, nickel-based ingot quality enhancement program, and critical process improvements, are strengthening the foundation for long-term growth. Through these initiatives, CSPM aims to further improve profitability, operational performance, and sustainable competitiveness.

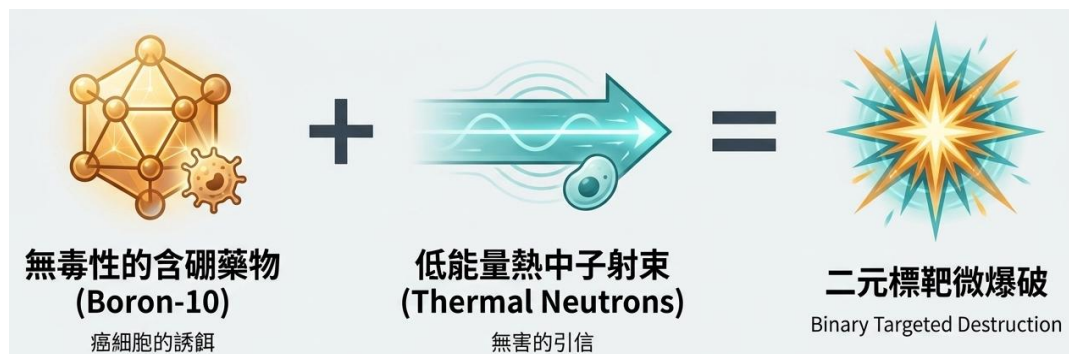


- ✓ 加速器型BNCT硼中子捕獲治療是利用低能量熱中子殺死腫瘤細胞卻又不嚴重影響正常組織細胞。為得到熱中子，加速器生成之高能中子需經調節器減速，中子調節器是由數種鋁基複合材料組合而成，鑫科獨家供應此調節器用生醫材料。

AB-Boron neutron capture therapy (BNCT) adopts the low energy thermal neutron ($< 1\text{eV}$) to kill tumor cells rather than normal cells. The high energy neutron must be deaccelerated through a moderator to get the thermal neutron. The moderator is mainly composed of various Al-base compounds, which are exclusively supplied by TTMC.

- ✓ 國內加速器型BNCT治療項目由2024年開始到現在，完成近20種以上的癌症，其中3成為頭頸，3成為腦，4成為其他如肺、乳等；下階段將規劃大腸、直腸等腹部類等癌症。

AB-BNCT treatment program has treated patients with more than 20 types of cancer, including head and neck, brain, lung, and breast. The next phase will focus on abdominal cancers, including colorectal and rectal cancers.





II. 重點產品 Product Highlights

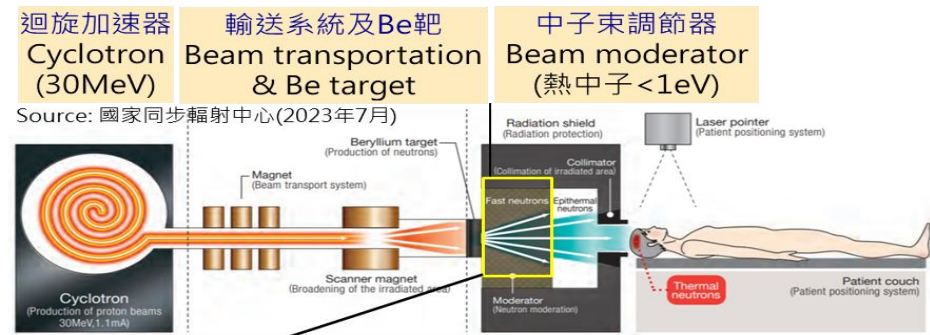
-生醫材料 Biomedical materials

- ✓ 2025年完成廠內大型熱壓設備建置，全製程自製生產，增加產品穩定性。

In 2025, TTMC completed the installation of large-scale HP equipment, enabling fully in-house production and increasing product stability.

- ✓ AB-BNCT設備已於2024年啟用，陸續取得相關證照等。搭配國內設備商陸續推廣與銷售，已取得明年穩定訂單，並陸續洽談後續訂單。為精進設備性能，持續與客戶探討材料優化方向。

AB-BNCT has enabled in 2024, and the relevant certificates and licenses are also obtained. In conjunction with the ongoing promotion and sales efforts by domestic equipment suppliers, TTMC have secured orders for next year and are currently in discussions for additional orders.



Neutron moderator is composed of Al-base compounds

II. 重點產品 Product Highlights

- 面板級扇外型封裝載板 FOPLP Carrier

- ✓ FOPLP (Fan-Out Panel-Level Packaging) 是一種半導體封裝方式，採用更大的「面板」來一次封裝更多晶片，希望在成本、效能和產能上取得平衡；且可協助解決AI 晶片需求。

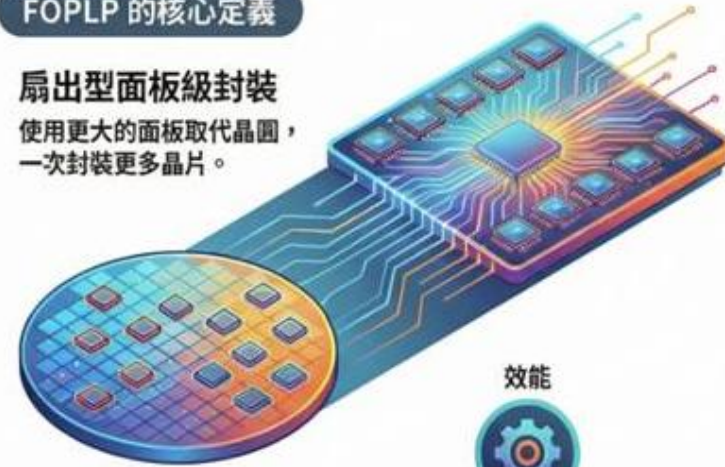
FOPLP is a semiconductor packaging method that uses larger "panels" to package more chips at once, aiming to achieve a balance between cost, performance, and production capacity; it can also help address the demand for AI chips.

- ✓ 鑫科成功開發與樹脂熱膨脹匹配之大尺寸金屬載板(700mmx700mm)，滿足FOPLP製程嚴苛需求，輔助FOPLP製程達成量產需求。

A dedicated alloy carriers with size up to 700mmx700mm featuring similar CTE to EMC are supplied to meet the severe requirement of FOPLP carrier.

FOPLP 的核心定義

扇外型面板級封裝
使用更大的面板取代晶圓，
一次封裝更多晶片。



追求三方的最佳平衡

旨在成本、效能與產能之間取得理想的平衡點。



FOPLP 是什麼？跟 AI 什麼關係？FOPLP 概念股有哪些？ - Win 投資



II. 重點產品 Product Highlights

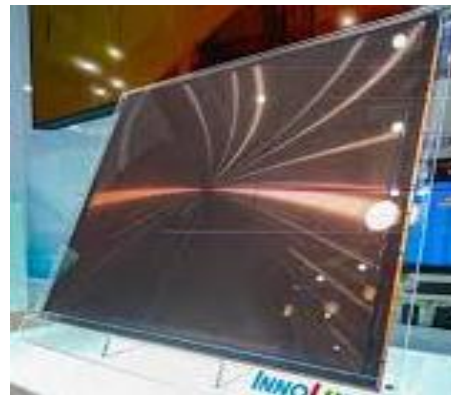
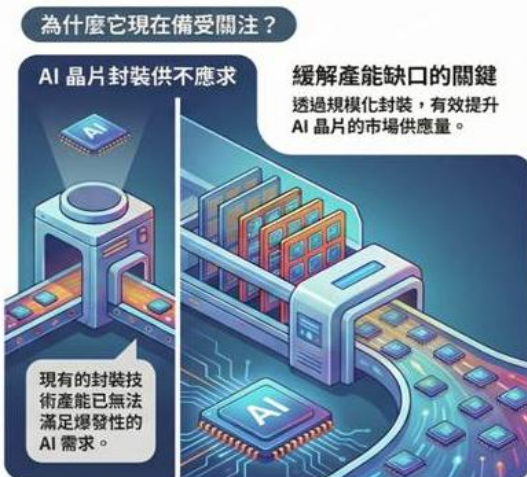
- 面板級扇出型封裝載板 FOPLP Carrier



- ✓ 配合客戶持續精進廠內機加工製程技術，以兼顧良率與生產速度為目標。於2024年起配合顧客需求，協助重工延伸使用壽命。

TTMC work with our customers to continuously improve in-house machining processes, with the goal of balancing yield rates and production speed. In 2024, TTMC will assist in extending the service life of heavy machinery in accordance with customer needs.

- ✓ 2025年持續穩定出貨外，2026年取得歐美大廠訂單，持續以現有製程技術拓展客戶。
In 2025-2026, the metal carrier plate is not only stable shipments, but also continuously promote to European and American customer. And continue to expand our customer base.



World largest FOPLP (700mm x 700mm)
area ~ 7 times of 300mm wafer

Source:三立新聞網(2023年9月)

FOPLP 是什麼？跟 AI 什麼關係？FOPLP 概念股有哪些？ - Win 投資



II. 重點產品 Product Highlights

-半導體金屬靶材/蒸鍍材 SEMI Metals Targets/Slugs



- ✓ 半導體應用產品分有靶材及蒸鍍材，應用由純矽跨足二、三類化合物。

Semiconductor application products are categorized into target materials and sputtering materials. In addition to first-generation silicon semiconductors, it is also advancing into the field of second- and third-generation compound semiconductors.

- ✓ 持續精進半導體靶材顯微組織與製程技術，強化製程穩定、機加工技術。

TTMC are continuously refining the microstructure and manufacturing processes, and enhancing process stability and machining techniques.

- ✓ 陸續完成廠內半導體設備建置，以全製程自製為目標，並持續自製研發拓展批量量產建置為主，產品則以以12吋晶圓用為目標。

TTMC have progressively completed the installation of semiconductor equipment to achieve the goal of in-house production. TTMC is focusing on establishing mass production capabilities, with a primary focus on products for 12-inch wafers.

- ✓ 蒸鍍材擴增設備，並穩定量產出貨，材料為Au, Ag等。半導體靶材則以8吋晶圓應用為主，陸續完成送樣、驗證及放量，材料為Ti, Ni-V, Ag等。

TTMC have expanded evaporation facilities with materials including Au and Ag. For semiconductor targets, TTMC primarily focus on 8-inch wafer applications, and have progressively achieve validation, and volume production, with materials including Ti, Ni-V, and Ag.





II. 重點產品 Product Highlights



-循環經濟企業社會責任/Circular Economy (Corporate Social Responsibility)

- ✓ 循環經濟的新商業模式不僅關乎廢棄物回收與再利用，更涵蓋創新商業模式的發展，包括節能與資源回收，以及產品壽命延長等面向。

The new business model of the circular economy is not just about the waste recycling and reuse, but also the development of innovative business models, including energy-saving and resource recovery and product life extension.

- ✓ 鑫科於循環經濟已進行多年，於貴金屬、殘靶等等，皆進行相關製程規劃。政策包含資源回收、循環供應、壽命延長等等。材料部分則由貴金屬-銀金，持續擴展鈦銅等金屬。

TTMC has been engaged in circular economy initiatives for many years, implementing relevant process design for precious metals, and used sputtering targets. The policy of circular economy is resource recovery, circular supply chains, and extended lifecycle management. The materials of circular economy are expand metals silver, gold, titanium and copper.

- ✓ 因應半導體高純原料成本，進行製程技術建置及初評，期望以此降低原料成本增加產品競爭力。

Due to the costs of high-purity raw materials for semiconductor application, TTMC is conducting preliminary evaluations to reduce costs and enhance product competitiveness.





III. 特殊合金商機 Opportunity of Specialty Alloy

-鈦材業務開拓 Open up Ti-related business

CSC GROUP

精材鈦材業務持續朝高值化產品與利基市場方向發展。面對終端需求疲弱及同業低價競爭等市場挑戰，公司除掌握海綿鈦價格上漲契機，適度調整產品售價以維持合理毛利外，亦持續推動產品品質提升與市場開拓。拓展成效摘要如下：

1. 純鈦大荒管品質改善已逐步展現成果，並積極拓展大型管坯市場。
2. TA10鈦合金荒管經製程優化後獲得客戶高度肯定，目前已全面推廣，成為重要高毛利產品之一。
3. GR9合金荒管訂單亦維持穩定成長，市場接受度持續提升。
4. TA2純鈦荒管已完成新客戶第二次試用驗證，後續若順利通過認證，將有助於進一步擴大出貨規模。

CSPM's titanium business continues to focus on the development of high-value-added products and niche markets. In response to weak downstream demand and intense price competition, the Company has leveraged the upward trend in sponge titanium prices to make appropriate selling price adjustments and maintain reasonable profit margins, while continuously improving product quality and expanding market presence. The summary of the results is as follows:

1. Significant progress has been achieved in enhancing the quality of large-diameter pure titanium hollows, and efforts are ongoing to expand the large billet market.
2. TA10 titanium alloy hollows, following process optimization, have received highly positive customer feedback and are now being fully promoted as one of CSPM's key high-margin products.
3. The orders for Grade 9 (GR9) alloy hollows have maintained steady growth, with increasing market acceptance and customer recognition.
4. TA2 pure titanium hollows have successfully completed a second round of qualification trials with a new customer. Upon successful certification, this program is expected to further increase shipment volumes.



III. 特殊合金商機 Opportunity of Specialty Alloy



- 鎳基合金業務開拓 Open up nickel-based alloy business

鎳基合金市場雖受需求疲弱及低價競爭影響，傳統通用型產品獲利空間持續受到壓縮，但高端應用市場仍具良好發展潛力。未來CSPM將持續聚焦半導體、新能源及高溫工業等高端應用市場，充分發揮真空熔煉、電渣重熔及鍛造製程優勢，推動產品結構由傳統材料供應商向高性能功能材料供應商轉型，逐步提升產品附加價值與整體獲利能力。

1. 在半導體領域，Ni93V7高純靶材及管靶具備非磁性、高導電性及良好鍍膜均勻性等特性，可用於半導體、電子元件及感測器產業，未來有機會成為公司重要成長動能。
2. 在新能源汽車領域，600及625合金爆破片材料具備優異耐蝕性及高溫強度，可應用於電池安全保護系統，隨著新能源車市場持續成長，需求前景值得期待。
3. 214及230等高溫合金具備優異抗氧化及耐高溫性能，可廣泛應用於熱處理設備、工業爐、石化及能源等高溫環境設備，市場進入門檻較高且產品附加價值優異。

Although the nickel-based alloy market continues to face weak demand and intense price competition, high-end application sectors still offer significant growth potential. CSPM will continue to focus on high-end markets such as semiconductors, new energy, and high-temperature industrial applications, leveraging its strengths in melting, ESR, and forging technologies to enhance product value and profitability.

1. Ni93V7 high-purity sputtering targets and tubular targets for semiconductor, electronic component, and sensor applications.
2. Alloy 600 and 625 burst disc materials for electric vehicle battery safety systems.
3. Alloy 214 and 230, which provide excellent oxidation resistance and high-temperature performance for heat-treatment equipment, industrial furnaces, and energy-related industries.





IV.營運展望 Operation Outlook



- 面對面板市場飽和與價格競爭，仍深化微細組織研究，以穩定產品品質為目標。

Amid panel market saturation and price competition, TTMC continues to deepen its microstructural research, aiming to stabilize product quality.

- 已完成熱壓生產設備建置，除全面滿足醫療級鋁基複合材料之需求外，將進一步擴大大型粉末冶金的產能與產品線。

Following the completion of our hot-pressing production equipment setup, TTMC is well-positioned to meet the demand for medical aluminum-composites while simultaneously scaling up large-scale powder metallurgy capacity and expanding product lines.

- 半導體產品推廣近5年，已陸續通過驗證與稽核，具備龐大成長潛力；將持續攜手戰略夥伴拓展市場。

With semiconductor products validated and audited over the past five years, we see strong growth potential and will continue to expand the market with strategic partners.



IV.營運展望 Operation Outlook



- 積極布局高純原料循環經濟，已完成初步製程技術研究，可望深化客我關係並提升產品競爭力。

Actively developing a circular economy for high-purity raw materials; preliminary process research is complete, promising closer customer ties and enhanced competitiveness.

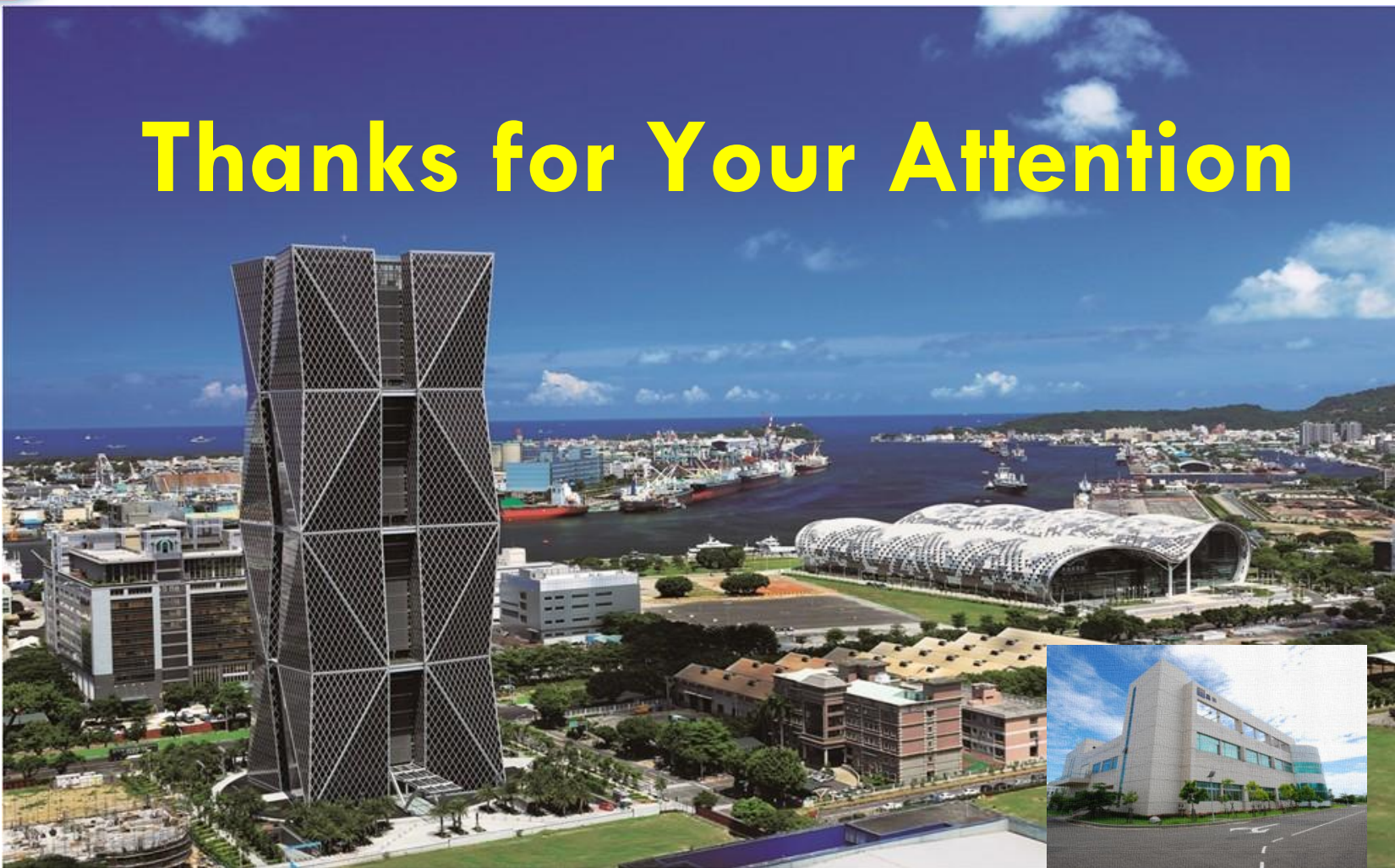
- 致力於 FOPLP 封裝載板之產量與良率提升，提供高性價比產品，並持續擴大產品應用與材料品項。

For FOPLP substrates, TTMC aims to boost in-house volume and yield for cost-competitive products, while broadening applications and material types.

- 持續擴大貴金屬零件清洗與靶材回收業務，深耕核心製程技術，全面拓展貴金屬市場。

TTMC will continue to expand our precious metal parts cleaning and sputtering target recycling businesses, solidifying our process technologies while broadening market presence in precious metals.

Thanks for Your Attention



New Vision Of Materials Application